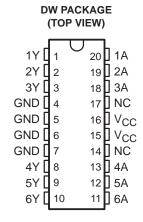
- CDC204 Replaces 74AC11204
- Low-Skew Propagation Delay Specifications for Clock-Driver Applications
- CMOS-Compatible Inputs and Outputs
- Flow-Through Architecture Optimizes PCB Layout
- Center-Pin V_{CC} and GND Pin Configurations Minimize High-Speed Switching Noise
- EPIC™ (Enhanced-Performance Implanted CMOS) 1-µm Process
- 500-mA Typical Latch-Up Immunity at 125°C
- Package Options Include Plastic Small-Outline Package (DW))



NC - No internal connection

description

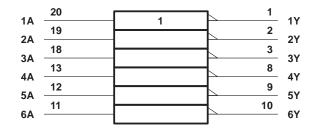
The CDC204 contains six independent inverters. The device performs the Boolean function $Y = \overline{A}$. It is designed specifically for applications requiring low skew between switching outputs.

The CDC204 is characterized for operation from $T_A = 25$ °C to 70°C.

FUNCTION TABLE

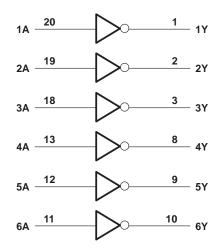
INPUT A	OUTPUT Y
Н	L
L	Н

logic symbol†



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)





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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	
Input voltage range, V _I (see Note 1)	\dots -0.5 V to V _{CC} + 0.5 V
Output voltage range, V _O (see Note 1)	$-0.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$)	±20 mA
Output clamp current, I _{OK} (V _O < 0 or V _O > V _{CC})	±50 mA
Continuous output current, I _O (V _O = 0 to V _{CC})	±50 mA
Continuous current through V _{CC} or GND	±150 mA
Maximum power dissipation at $T_A = 55^{\circ}C$ (in still air) (see Note 2)	1.6 W
Storage temperature range, T _{stq}	65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
 - 2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils. For more information, refer to the *Package Thermal Considerations* application note in the 1994 *ABT Advanced BiCMOS Technology Data Book*, literature number SCBD002B.

recommended operating conditions

			MIN	NOM	MAX	UNIT
Vcc	Supply voltage		4.75	5	5.25	V
VIH	High-level input voltage	V _{CC} = 4.75 V	3.3			V
		V _{CC} = 5.25 V	3.7			V
VIL	Low-level input voltage	V _{CC} = 4.75 V			1.4	V
		V _{CC} = 5.25 V			1.6	
٧ _I	Input voltage				VCC	V
IOH High-level output current	High level output ourrent	V _{CC} = 4.75 V			-24	mA
	riigh-level output current	V _{CC} = 5.25 V			-24	IIIA
lOL	Low-level output current	V _{CC} = 4.75 V			24	mA
		V _{CC} = 5.25 V			24	
Δt/Δν	Input transition rise or fall rate		0		10	ns/V
fclock	Input clock frequency				80	MHz
TA	Operating free-air temperature		25		70	°C



electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER	TEST CON	DITIONS	T _A †	MIN	TYP	MAX	UNIT	
Vон	High-level voltage output	I _{OH} = - 50 μA	V _{CC} = 4.75 V	25°C	4.65				
				Full range	4.65				
			V _{CC} = 5.25 V	25°C	5.15			V	
				Full range	5.15				
		I _{OH} = – 24 mA	V _{CC} = 4.75 V	25°C	4.19				
				Full range	4.05				
			V _{CC} = 5.25 V	25°C	4.68				
				Full range	4.55				
		$I_{OH} = -75 \text{ mA}^{\ddagger}$,	V _{CC} = 5.25 V	Full range	3.6				
	Low-level voltage output	Ι _{ΟL} = 50 μΑ	V _{CC} = 4.75 V	25°C			0.1		
				Full range			0.1		
			V _{CC} = 5.25 V	25°C			0.1		
				Full range			0.1		
VOL		I _{OL} = 24 mA	V _{CC} = 4.75 V	25°C			0.36	V	
				Full range			0.44	1	
			V _{CC} = 5.25 V	25°C			0.36		
				Full range			0.44		
		$I_{OL} = 75 \text{ mA}^{\ddagger}$,	V _{CC} = 5.25 V	Full range			1.65		
t _I	Input current	V _I = V _{CC} or GND	V _{CC} = 5.25 V	25°C			±0.1	μΑ	
				Full range			±1	μΑ	
loo	Supply current	$V_I = V_{CC}$ or GND, $I_O = 0$	$V_{CC} = 5.25 \text{ V},$	25°C			4	μΑ	
ICC				Full range			40	μΑ	
Ci	Input capacitance	$V_I = V_{CC}$ or GND,	$V_{CC} = 5 V$	25°C		4		pF	

[†] Full range is $T_A = 25^{\circ}C$ to $70^{\circ}C$.

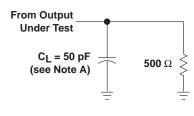
switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.25 V (see Note 3 and Figures 1 and 2)

PARAMETER		FROM (INPUT)	TO (OUTPUT)	MIN	MAX	UNIT
^t PLH	Propagation delay time, low-to-high level (see Figure 1)	^	V	3.7	5.7	ns
tPHL	Proagation delay time, high-to-low level (see Figure 1)	А	Ţ	2.9	5.7	115
tsk(o)	Output skew time (see Figure 2)	А	Υ		1	ns

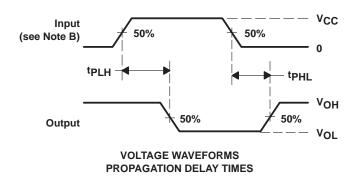
NOTE 3: All specifications are valid only for all outputs switching simultaneously and in phase.

[‡] Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

PARAMETER MEASUREMENT INFORMATION



LOAD CIRCUIT

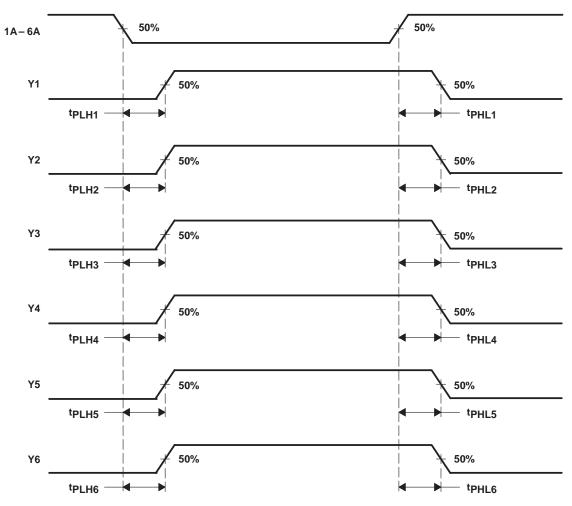


NOTES: A. C_L includes probe and jig capacitance.

- B. Input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_{O} = 50 Ω , t_{f} = 3 ns, t_{f} = 3 ns.
- C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION



- NOTE A: Output skew, $t_{SK(0)}$, is calculated as the greater of:

 The difference between the fastest and slowest of t_{PHLn} (n = 1, 2, ..., 6)

 The difference between the fastest and slowest of t_{PLHn} (n = 1, 2, ..., 6)

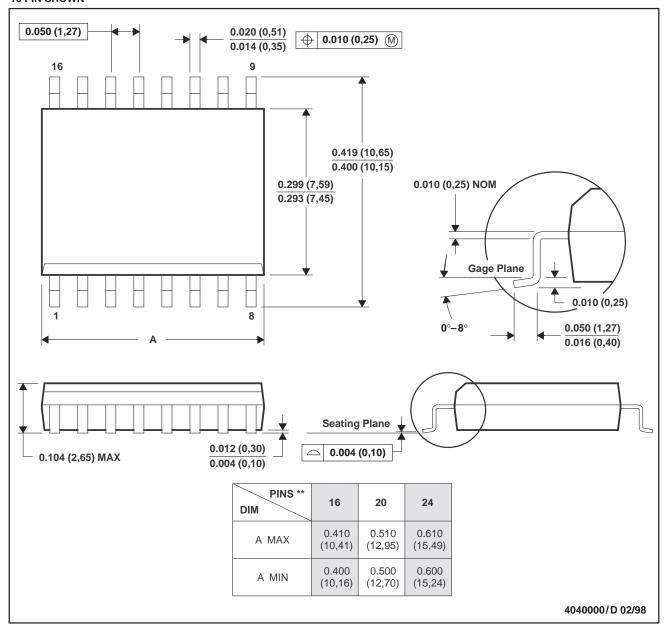
Figure 2. Waveforms for Calculation of $t_{sk(o)}$

MECHANICAL INFORMATION

DW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

16 PIN SHOWN



 $\label{eq:notes:notes} \mbox{NOTES:} \ \ \mbox{A.} \ \ \mbox{All linear dimensions are in inches (millimeters)}.$

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013



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